

CLAIMS

What is claimed is:

1. A method of manufacturing a wiring board, comprising:
softening a receiving layer formed of a thermoplastic resin by applying heat;
forming an interconnect layer on the receiving layer which is softened by the application of heat using a solvent containing conductive particles; and
causing the conductive particles to be bonded together by heating the interconnect layer.
2. The method of manufacturing a wiring board as defined in claim 1,
wherein the interconnect layer is formed by ejecting the solvent containing the conductive particles.
3. The method of manufacturing a wiring board as defined in claim 1,
wherein the receiving layer is formed on a base material.
4. The method of manufacturing a wiring board as defined in claim 1, further comprising:
removing the base material from the receiving layer after causing the conductive particles to be bonded together.
5. A wiring board manufactured by the method of manufacturing a wiring board as defined in claim 1.

6. A semiconductor device comprising:
a wiring board as defined in claim 5; and
a semiconductor chip electrically connected with the wiring board.

7. An electronic instrument comprising the semiconductor device as defined in claim 6.

8. A method of manufacturing a wiring board, comprising:
forming a first interconnect layer on a first receiving layer formed of a thermoplastic resin which has been in a softened state by using a solvent containing conductive particles;

forming a second receiving layer in a softened state on the first receiving layer and the first interconnect layer by using a thermoplastic resin;

forming a second interconnect layer on the second receiving layer which has been in the softened state by using a solvent containing conductive particles;
and

causing the thermoplastic resins of the first and second receiving layers to be softened and the conductive particles to be bonded together in a connecting portion of the first and second interconnect layers by applying heat.

9. The method of manufacturing a wiring board as defined in claim 8,

wherein the conductive particles included in the first interconnect layer are dispersed in the solvent in a state in which each of the conductive particles is covered with a coating material for preventing a reaction between the conductive particles, and

wherein the method further includes decomposing the coating material by heating the first interconnect layer before forming the second receiving layer.

10. The method of manufacturing a wiring board as defined in claim 8,

wherein the first and second interconnect layers are formed by ejecting the solvent containing the conductive particles.

11. The method of manufacturing a wiring board as defined in claim 8,

wherein the first receiving layer is formed on a base material.

12. The method of manufacturing a wiring board as defined in claim 8, further comprising:

removing the base material from the first receiving layer after causing the conductive particles to be bonded together in the connecting portion of the first and second interconnect layers.

13. A wiring board manufactured by the method of manufacturing a wiring board as defined in claim 8.

14. A semiconductor device comprising:

a wiring board as defined in claim 13; and

a semiconductor chip electrically connected with the wiring board.

15. An electronic instrument comprising the semiconductor device as defined in claim 14.